

### PMP10898A BOM\_6V

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
2	C15 C32	0.1uF	Capacitor, Ceramic Chip, 50V, X7R, 15%	603	Std	Std
2	C10 C34	1000pF	Capacitor, Ceramic Chip, 50V, X7R, 15%	603	STD	STD
1	C23	470pF	Capacitor, Ceramic Chip, 50V, X7R, 15%	603	Std	Std
1	C16	10pF	Capacitor, Ceramic Chip, 50V, NPO, 10%	603	Std	Std
1	C37	220pF	Capacitor, Ceramic Chip, 50V, X7R, 15%	603	Std	Std
1	C33	1uF	Capacitor, Ceramic Chip, 16V, X5R, 20%	603	Std	Std
1	C35	4.7uF	Capacitor, Ceramic, 16V, X7R, 20%	805	STD	STD
1	C17	1uF	Capacitor, Ceramic Chip, 100V, X7R, 15%	1206	Std	Std
2	C4-5	2.2uF	Capacitor, Ceramic Chip, 100V, ±10%	1210	Std	STD
2	C26 C28	22uF	Capacitor, Ceramic Chip, 16V, ±20%	1210	Std	STD
1	C22	680uF	Capacitor, ZLG 680uF, 10V 0.028 ohm	8mm by 16mm	ZLG 10V 680uF 8x16 or 10x12	Rubycon
1	C12	470uF	Capacitor, ZLH +/-20%, 63V, 1.99A, 0.043 ohm	12.5x25mm	ZLH 63V 12.5x25mm 470uF	Rubycon
1	J1	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	L2	22 uH	14A heating, 18.7A sat, 16mOhms	15.4 x 16.4 x 10 mm	XAL1510-223ME	Coilcraft
1	R6	0	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	R11	10k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	5.1	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	R14	2.2	Resistor, Chip, 1/16W, 5%	603	Std	Std
1	R20	100k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R18	13k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	20.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R12	162k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R22	24.9k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R21	499	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R19	11.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R17	63.4k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	604k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	0	Resistor, Chip, 1/16W, 5%	805	Std	Std
1	R100	10	Resistor, Chip, 1/4W, 5%	1206	Std	Std
2	J2-3	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	OST
6	TP1-2 TP4 TP6-7 TP12	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	TP3 TP9-10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP11	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	U1	TPS40170RGY	IC, 4.5V - 60V Wide Input Sync. PWM Buck Controller	QFN-20	TPS40170RGY	TI
2	Q1 Q3	CSD19534Q5A	MOSFET, Nch, 100V, 14.1 milliohm	TDSON-8	CSD19534Q5A	TI
1	PCB	PMP6680 REV A	PCB: 3.8" by 3.2" by 0.063" 4 Layers			any

Notes:

- On PCB PMP6680A jumper TP1 to junction of R2/R3
- Jumper J1 pin 1 to pin 2
- On PCB PMP6680A jumper out L1 with wide strap tested with size 2010 for R100, but it can be size 1206 or 1210
- On PCB PMP6680: R100 & C100 added by hand

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